

描述 / Descriptions

SOD-323 塑封封装 快速开关二极管。

Fast Switching Diodes in a SOD-323 Plastic Package.

特征 / Features

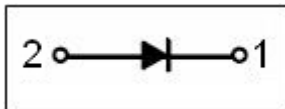
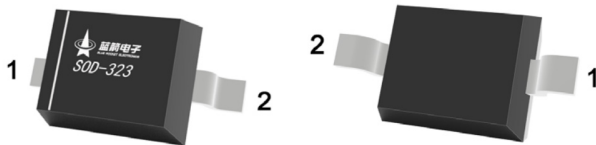
快速反向恢复时间，无卤产品。

Fast reverse recovery time, HF Product.

用途 / Applications

用于小信号处理。

Small signal diode.

内部等效电路 / Equivalent Circuit**引脚排列 / Pinning**

PIN1:Cathode

PIN2:Anode

印章代码 / Marking

Marking	HA2
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极限参数 / Absolute Maximum Ratings(Ta=25°C)

参数 Parameter	符号 Symbol	数值 Rating	单位 Unit
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	100	V
Maximum RMS voltage	V_{RMS}	75	V
Average Rectified Forward Current	$I_{F(AV)}$	150	mA
Non-reptitive Peak Forward Surge Current	$I_{FSM} (t=1s)$	0.5	A
	$I_{FSM} (t=1ms)$	1	
	$I_{FSM} (t=1\mu s)$	4	
Total Power Dissipation	P_{tot}	400	mW
Typical Thermal Resistance ⁽¹⁾	$R_{\theta JA}$	340	°C/W
	$R_{\theta JC}$	120	
Operating and Storage Temperature Range	T_j, T_{stg}	-55~+150	°C

Note :

(1) P.C.B. mounted with 5*5mm copper pad areas.

电性能参数 / Electrical Characteristics(Ta=25°C)

参数 Parameter	符号 Symbol	测试条件 Test Conditions	最小值 Min	典型值 Typ	最大值 Max	单位 Unit
Reverse Breakdown Voltage	$V_{(BR)R}$	$I_R=1\mu A$	100			V
Maximum Forward Voltage	V_F	$I_F=1mA$			0.715	V
		$I_F=10mA$			0.855	
		$I_F=50mA$			1.00	
		$I_F=150mA$			1.25	
Peak Reverse Current	I_R	$V_R=20V$			0.025	μA
		$V_R=75V$			1	
		$V_R=25V \quad T_j=150^\circ C$			30	
		$V_R=75V \quad T_j=150^\circ C$			50	
Typical Junction Capacitance	C_j	$f=1MHz \quad V_R=0V$		2		pF
Maximum Reverse Recovery Time	t_{rr}	$I_F=I_R=10mA \quad I_{rr}=0.1 \times I_R$ $R_L=100\Omega$			4	ns

电参数曲线图 / Electrical Characteristic Curve

Fig.1 Power Derating Curve

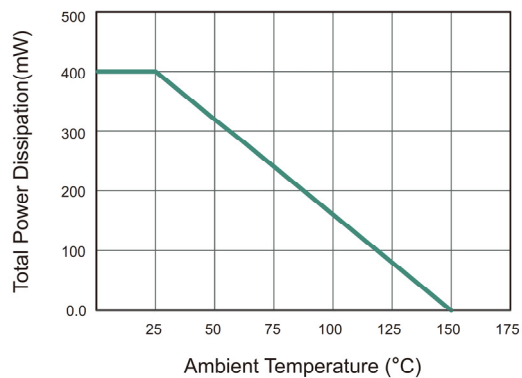


Fig.2 Typical Reverse Characteristics

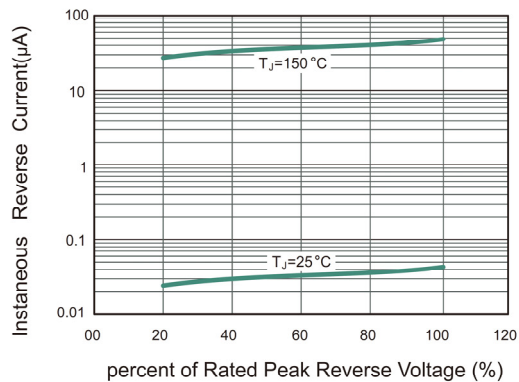


Fig.3 Typical Instantaneous Forward Characteristics

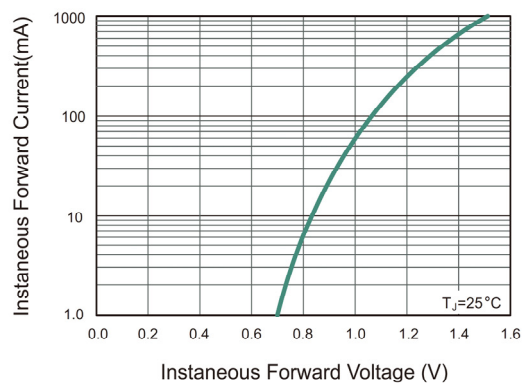
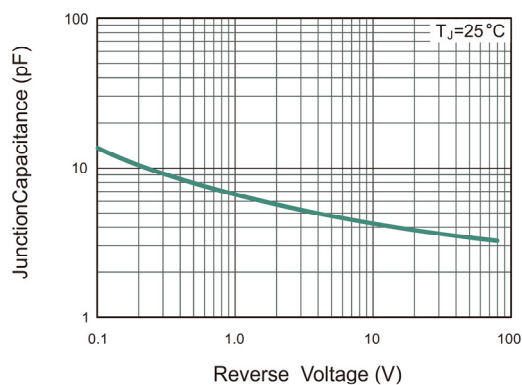
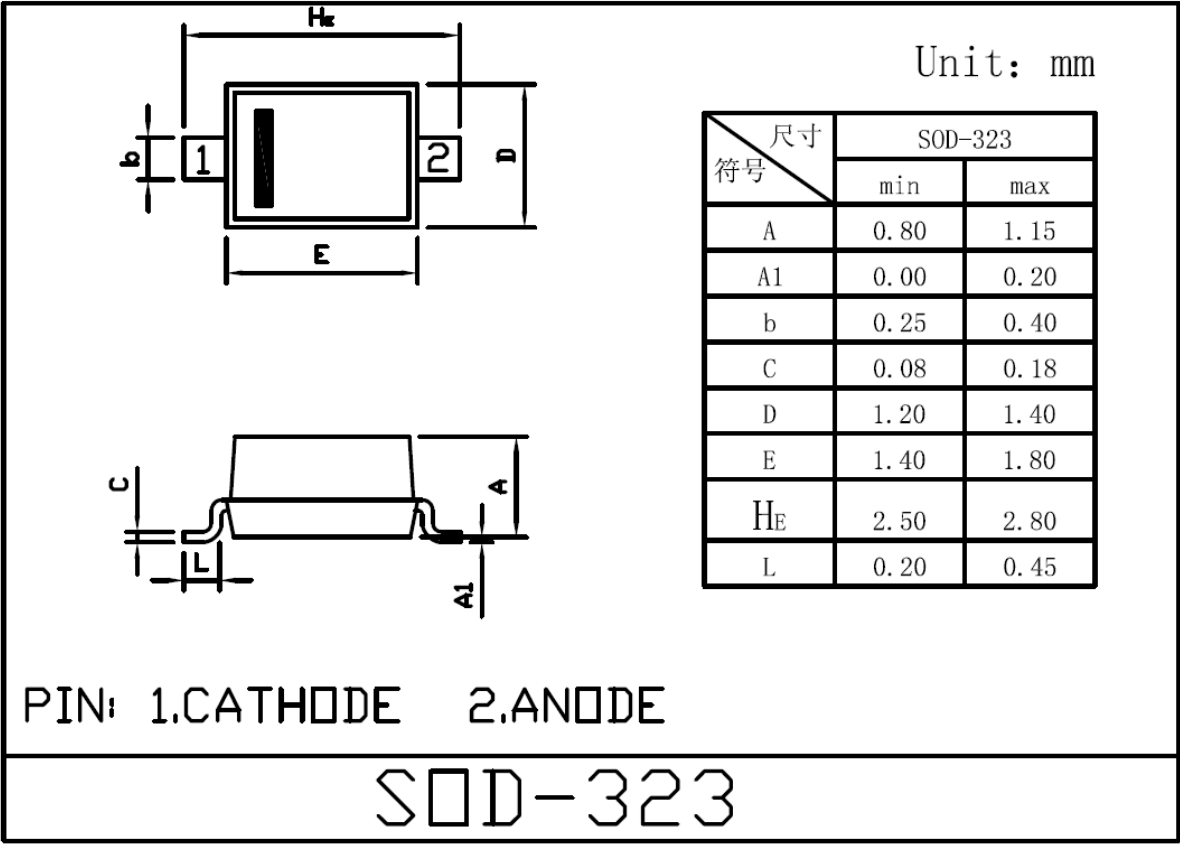


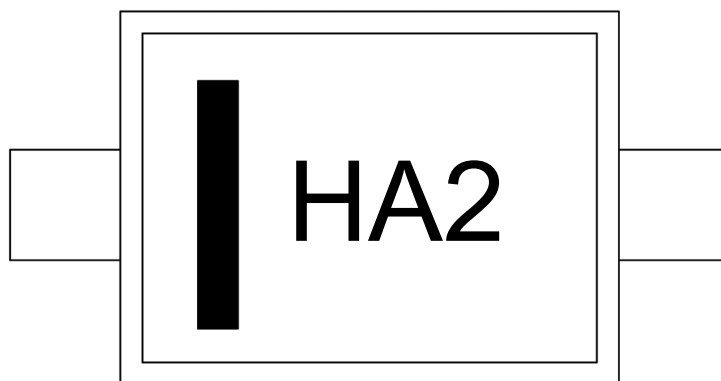
Fig.4 Typical Junction Capacitance



外形尺寸图 / Package Dimensions



印章说明 / Marking Instructions



说明：

H： 为公司代码

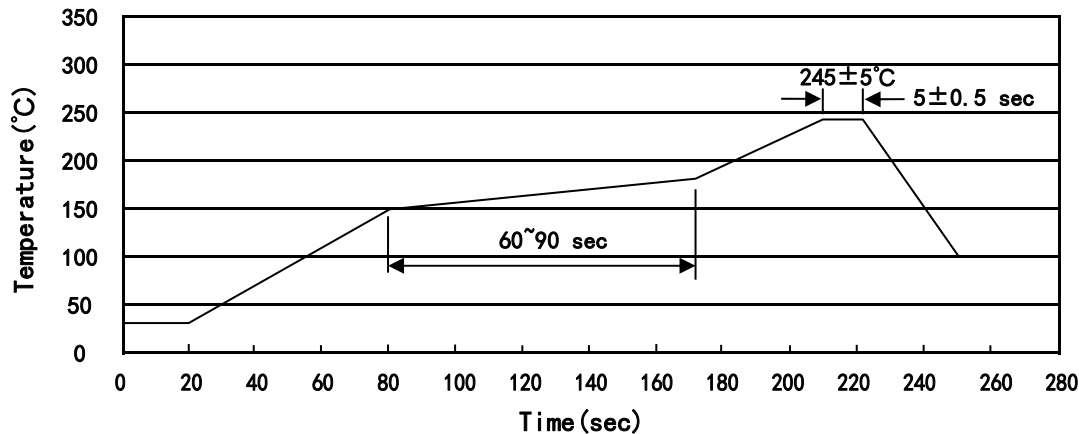
A2： 为型号代码

Note:

H: Company Code

A2: Product Type Code

回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)



说明：

- 1、预热温度 150~180°C，时间 60~90sec;
- 2、峰值温度 245±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2~10°C/sec.

Note:

- 1.Preheating:150~180°C, Time:60~90sec.
- 2.Peak Temp.:245±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度：260±5°C

时间：10±1 sec.

Temp.:260±5°C

Time:10±1 sec

包装规格 / Packaging SPEC.

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOD-323	3,000	10	30,000	6	180,000	7" ×8	180×120×180	390×385×205

使用说明 / Notices